

Supplemental Preliminary Amendment

Applicant: Michael Bauer et al.

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Title: SUPPORT WITH SOLDER BALL ELEMENTS AND A METHOD FOR POPULATING SUBSTRATES WITH SOLDER BALLS

IN THE ABSTRACT

Please replace the Abstract with the following newly written Abstract:

SUPPORT WITH SOLDER BALL ELEMENTS AND METHOD FOR LOADING SUBSTRATES WITH BALL CONTACTS

Abstract

The invention relates to a support (4) with solder ball elements (44) for loading substrates (2) with ball contacts is disclosed. Furthermore, One embodiment, the invention relates to provides a system for loading substrates (2) with ball contacts and to a method for loading substrates (2) with ball contacts. For this purpose, The support (4) has a layer of adhesive (5) applied on one side, the layer of adhesive (5) losing its adhesive force to the greatest extent when irradiated. Furthermore, The support (4) has solder ball elements (44), which are arranged closely packed in rows (6) and columns (7) on the layer of adhesive (5) in a prescribed pitch (46) for a semiconductor chip or a semiconductor component.

[[Figure 1]]